

## 128-Channel Serial to Parallel Converter with Push-Pull Outputs

### Features

- 128 High-Voltage Channels
  - Up to 80V Operating Output Voltage
  - 30 mA Peak Output Sink/Source Current
  - Output Diodes to Ground for Efficient Power Recovery
- Four Separate Shift Registers
  - Clockwise and Counter-Clockwise Data Shifting via DIR Pin
- 40 MHz Data Rate

### Applications

- Inkjet Printer Driver
- Plasma Display Driver
- 3D Printer Driver

### Related Devices

- **HV582:** 96-Channel Serial to Parallel Converter with Push-Pull Outputs

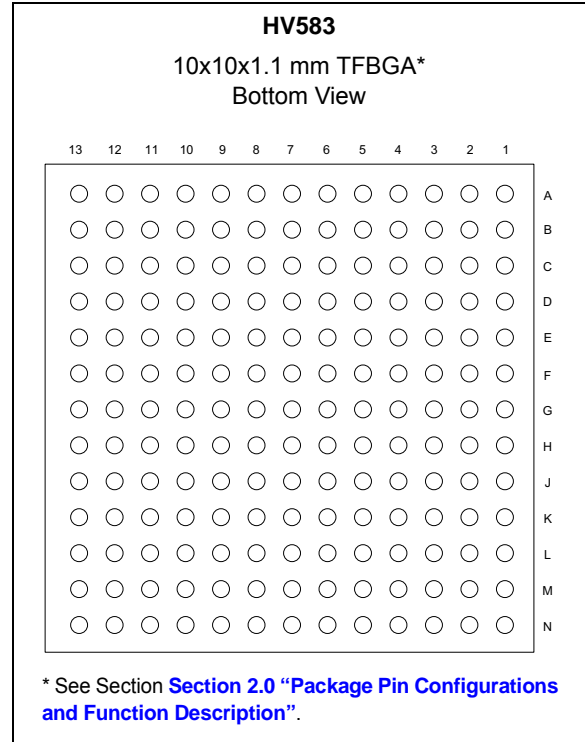
### Description

HV583 is a unipolar, 128-channel low-voltage serial to high-voltage parallel converter with push-pull outputs. This device has been designed for applications requiring multiple high-voltage outputs with current sinking and sourcing capabilities, such as plasma displays and Inkjet printers.

The device consists of four parallel 32-bit shift registers, a 128-bit latch and 128 high-voltage outputs. Data can be input at 40 MHz or up to 25 MHz when cascaded in a multiple device configuration.

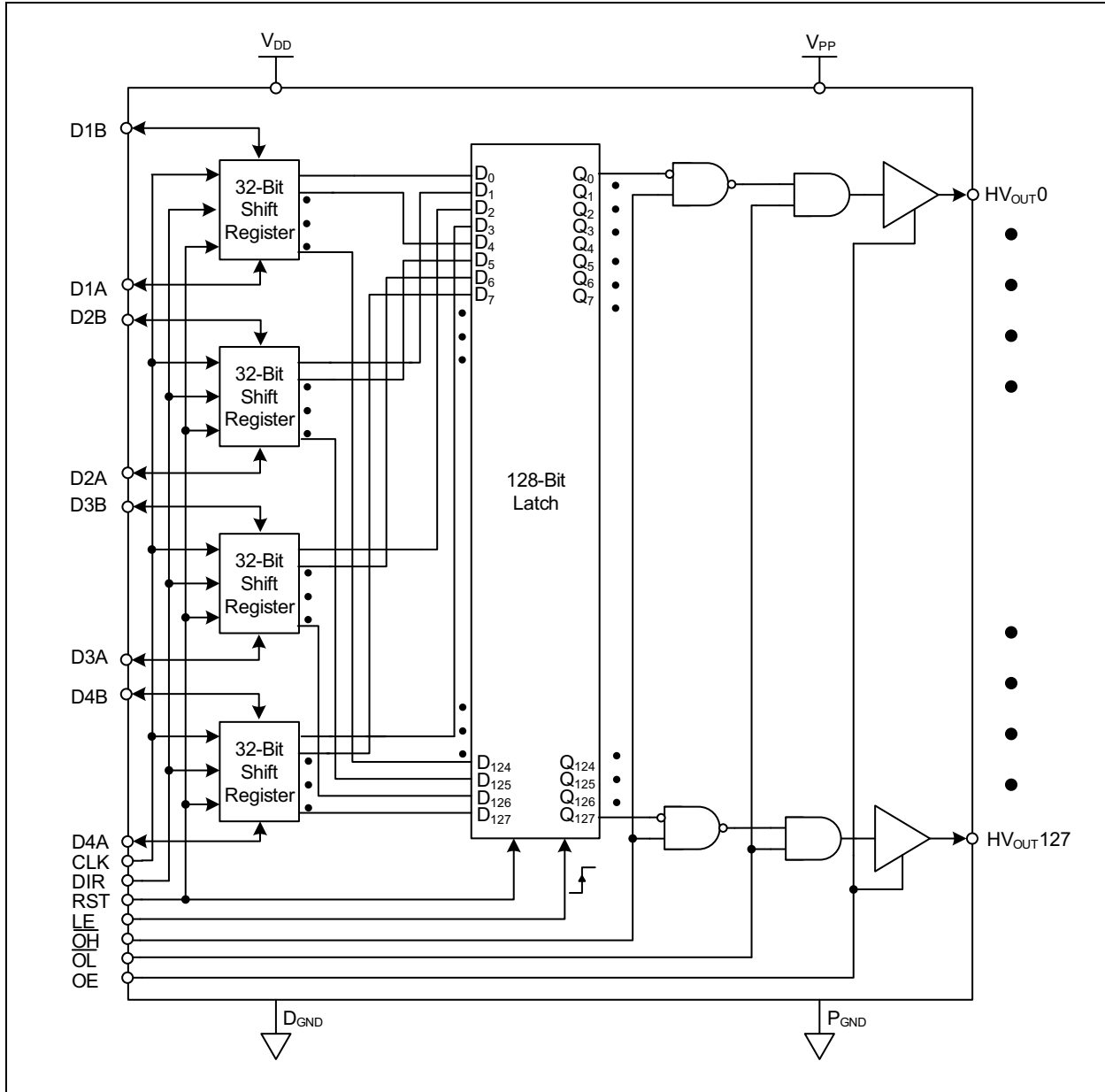
HV583 is offered in a 169-ball 10 x 10 x 1.1 mm TFBGA package.

### Package Type



# HV583

## Block Diagram



## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Rating†

Supply Voltage $V_{DD}$ .....	-0.5V to +6.5V
High-Voltage Supply $V_{PP}$ .....	-0.5V to +90V
Output Sink and Source Current $I_{OUT}$ .....	-65 mA to +40 mA
Output Body Diode Current $I_{DIODE}$ .....	-65 mA to +65 mA
Logic Input Voltage.....	-0.5V to $V_{DD}$ +0.5V
Operating Junction Temperature.....	-25°C to +125°C
Storage Temperature .....	-40°C to +150°C

†**Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability. Device is ESD sensitive. Use appropriate ESD precautions.

### RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
High-Voltage Supply	$V_{PP}$	15	-	80	V	
Low-Voltage Supply	$V_{DD}$	4.5	5.0	5.5	V	
HV <sub>OUT</sub> Peak Output Current	$I_{OUT}$	-30	-	30	mA	
$V_{PP}$ Power Supply Slew Rate	SR	-	-	8.0	V/ $\mu$ s	
Clock Frequency	$f_{CLK}$	-	-	40	MHz	Data Read
		-	-	25	MHz	Cascaded Devices

**TABLE 1-1: POWER SEQUENCES**

Sequence Type	Steps
Power- Up Sequence	<ol style="list-style-type: none"> <li>1. Connect Ground.</li> <li>2. Apply <math>V_{DD}</math>.</li> <li>3. Set All Inputs (Data, CLK, etc.) to a known state.</li> <li>4. Apply <math>V_{PP}</math></li> </ol>
Power- Down Sequence	Repeat the Power-Up sequence in reverse order.

### DC ELECTRICAL CHARACTERISTICS

**Electrical specifications:** Unless otherwise specified,  $T_A = T_J = +25^\circ\text{C}$ ,  $V_{DD} = 5.0\text{V}$  and  $V_{PP} = 80\text{V}$ .

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
$V_{PP}$ Quiescent Supply Current	$I_{PPQ}$	—	—	10	$\mu\text{A}$	
$V_{DD}$ Quiescent Supply Current	$I_{DDQ}$	—	—	10	$\mu\text{A}$	
High-Level Output Voltage	$HV_{OH}$	73	76	—	V	$I_{OUT} = 15\text{ mA}$ , $V_{PP} = 80\text{V}$
		10	—	—		$I_{OUT} = 10\text{ mA}$ , $V_{PP} = 20\text{V}$
Output P-Channel Body Diode	$HV_{OHD}$	—	—	81.5	V	$I_{OUT} = -30\text{ mA}$ , $V_{PP} = 80\text{V}$ ( <b>Note 1</b> )
Low-Level Output Voltage	$HV_{OL}$	—	3.0	6.0	V	$I_{OUT} = -15\text{ mA}$
Output N-Channel Body Diode	$HV_{OLD}$	-1.5	—	—	V	$I_{OUT} = 30\text{ mA}$ ( <b>Note 1</b> )

**Note 1:** Specification is for design guidance only.

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## DC ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical specifications: Unless otherwise specified, $T_A = T_J = +25^\circ\text{C}$ , $V_{DD} = 5.0\text{V}$ and $V_{PP} = 80\text{V}$ .						
Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Logic Input High Voltage	$V_{IH}$	2.3	—	$V_{DD}$	V	$V_{DD} = 4.5\text{V to } 5.5\text{V}$
Logic Input Low Voltage	$V_{IL}$	0	—	0.7		$V_{DD} = 4.5\text{V to } 5.5\text{V}$
Logic Input High Current	$I_{IH}$	—	—	1.0	$\mu\text{A}$	$V_{IH} = 5.3\text{V}$ , $V_{DD} = 5.0\text{V}$
		10	30	60		$V_{IH} = 5.0\text{V}$ , for DIR only
Logic Input Low Current	$I_{IL}$	-1.0	—	—		$V_{IL} = -0.3\text{V}$
Logic Output High	$V_{OH}$	4.5	—	—	V	$I_{OUT} = 1.0\text{ mA}$
Logic Output Low	$V_{OL}$	—	—	0.5		$I_{OUT} = -1.0\text{ mA}$

**Note 1:** Specification is for design guidance only.

## AC ELECTRICAL CHARACTERISTICS

Electrical specifications: Unless otherwise specified $T_A = T_J = 25^\circ\text{C}$ , $V_{DD} = 5.0\text{V}$ and $V_{PP} = 80\text{V}$							
Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions	
Clock Pulse Width, High and Low <sup>(1)</sup>	$t_{wCLK}$	10	—	—	ns	$V_{DD} = 4.5\text{V to } 5.5\text{V}$ $T_J = -25^\circ\text{C to } 125^\circ\text{C}$	
LE Pulse Width, High and Low <sup>(2)</sup>	$t_{wLE}$	10	—	—			
Setup Time, DnA/B to CLK <sup>(1)</sup>	$t_{su1}$	5	—	—			
Setup Time, CLK to LE <sup>(1)</sup>	$t_{su2}$	10	—	—			
Setup Time, LE to $\overline{OL}$ , $\overline{OH}$ <sup>(1)</sup>	$t_{su3}$	25	—	—			
Hold Time, CLK to DnA/B <sup>(1)</sup>	$t_{h1}$	5	—	—			
Hold Time, LE to CLK <sup>(1)</sup>	$t_{h2}$	10	—	—			
CLK to DnA/B (High-to-Low)	$t_{pdHL}$	—	—	25			$C_L = 15\text{ pF}$
CLK to DnA/B (Low-to-High)	$t_{pdLH}$	—	—	25			$C_L = 15\text{ pF}$
LE, $\overline{OL}$ , $\overline{OH}$ to HV <sub>OUTn</sub> (High-to-Low)	$t_{pHL}$	—	—	150			$C_L = 50\text{ pF}$
LE, $\overline{OL}$ , $\overline{OH}$ to HV <sub>OUTn</sub> (Low-to-High)	$t_{pLH}$	Typ-40	$t_{pHL} + t_f$	Typ+40			$C_L = 80\text{ pF}$
OE to HV <sub>OUTn</sub> (High-to-Low)	$t_{pHZL}$	—	—	150			$C_L = 50\text{ pF}$
OE to HV <sub>OUTn</sub> (Low-to-High)	$t_{pLZH}$	Typ-40	$t_{pHL} + t_f$	Typ+40			$C_L = 80\text{ pF}$
OE to HV <sub>OUTn</sub> (High-to-Low)	$t_{pHZ}$	—	—	300			$R_L = 10\text{K}$ , $C_L = 50\text{ pF}$
OE to HV <sub>OUTn</sub> (Low-to-High)	$t_{pLZ}$	—	—	300	$R_L = 10\text{K}$ , $C_L = 50\text{ pF}$		
Rise Time HV <sub>OUTn</sub>	$t_r$	—	—	120	$C_L = 50\text{ pF}$		
Fall Time HV <sub>OUTn</sub>	$t_f$	—	—	120	$C_L = 50\text{ pF}$		

**Note 1:** Specification is obtained by characterization and is not 100% tested.





**Note 2:** Specification is for design guidance only.

## TEMPERATURE SPECIFICATIONS



Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
<b>Temperature Ranges</b>						
Operating Junction Temperature	$T_J$	-25	—	+125	$^\circ\text{C}$	
Storage Temperature	$T_A$	-40	—	+150	$^\circ\text{C}$	
<b>Package Thermal Resistance</b>						
Thermal Resistance, 169-Ball TFBGA	$\theta_{JA}$	—	27	—	$^\circ\text{C/W}$	

## 1.1 Logic Characteristics

**TABLE 1-2: SHIFT REGISTER TRUTH TABLE**

DIR	CLK	State	Direction
L or Open		Shift	DnB to DnA
L or Open		Hold	DnB to DnA
H		Shift	DnA to DnB
H		Hold	DnA to DnB

**Legend:**

- D = Data
- H = Level High
- L = Level Low
- X = Don't Care
- Z = High Impedance
-  = Low-to-High Transition
-  = High-to-Low Transition





**TABLE 1-3: LATCH TRUTH TABLE**

LE	Output State of Latch
L to H	Latch Execution
H to L	Hold

**TABLE 1-4: HV<sub>OUTn</sub> TRUTH TABLE**

OE	$\overline{OL}$	$\overline{OH}$	DnA/DnB	HV <sub>OUTn</sub>
L	X	X	X	Z
H	L	X	X	L
H	H	L	X	H
H	H	H	L	L
H	H	H	H	H

**TABLE 1-5: RESET TRUTH TABLE**

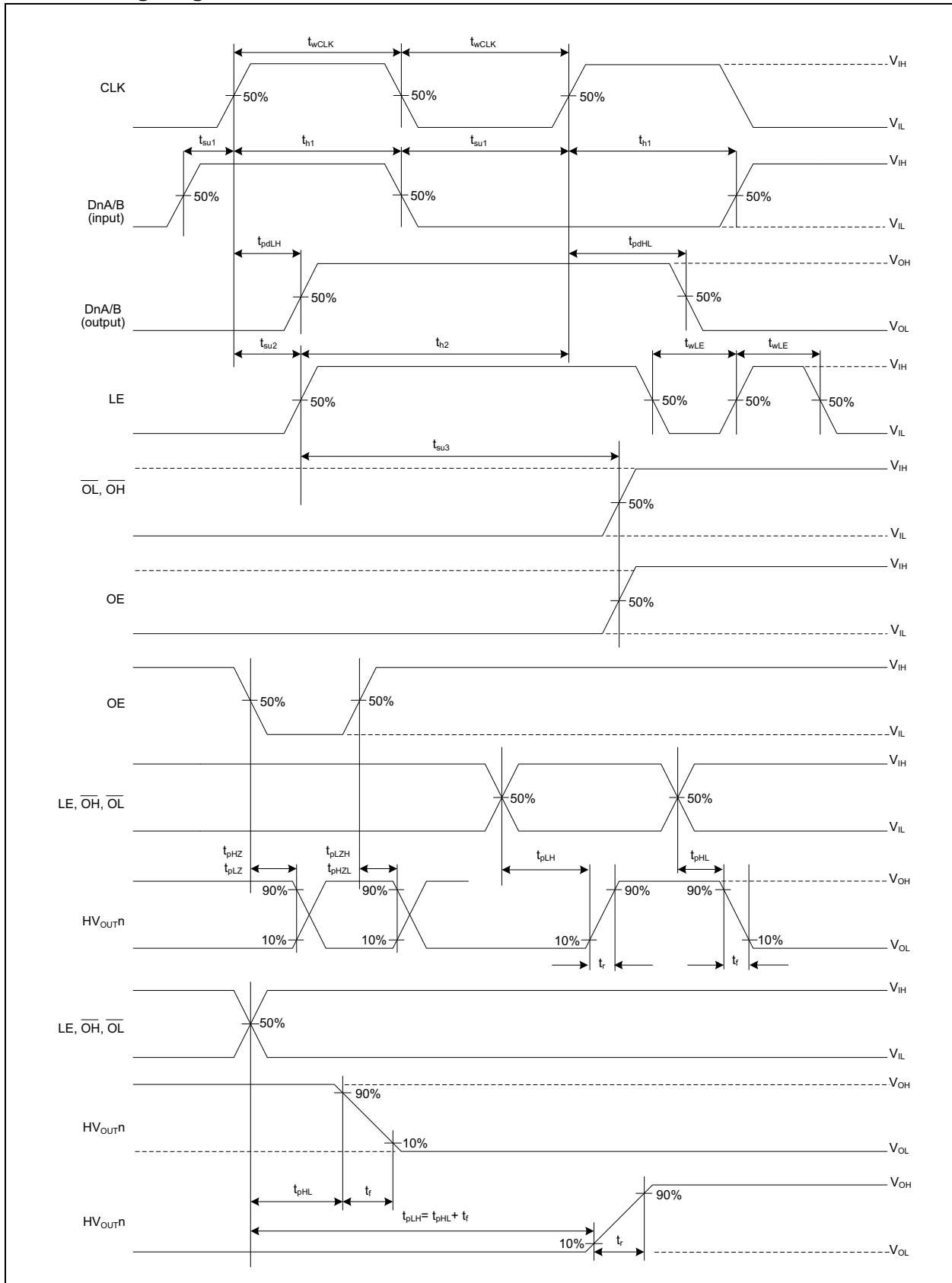
RST	CLK	LE	Shift Register	Latches
0		X	Shift	X
0	X		X	Latch
1		X	Clear	X
1	X		X	Clear

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**TABLE 1-6: OUTPUT SHIFT OPERATION**

<b>Input</b>	<b>Output</b>	<b>DIR</b>	<b>Shift Operation</b>
D1A = D	D1B	H	D to D124...D0 to D1B
D2A = D	D2B	H	D to D125...D1 to D2B
D3A = D	D3B	H	D to D126...D2 to D3B
D4A = D	D4B	H	D to D127...D3 to D4B
D1B = D	D1A	L or Open	D to D0...D124 to D1A
D2B = D	D2A	L or Open	D to D1...D125 to D2A
D3B = D	D3A	L or Open	D to D2....D126 to D3A
D4B = D	D4A	L or Open	D to D3.....D127 to D4A

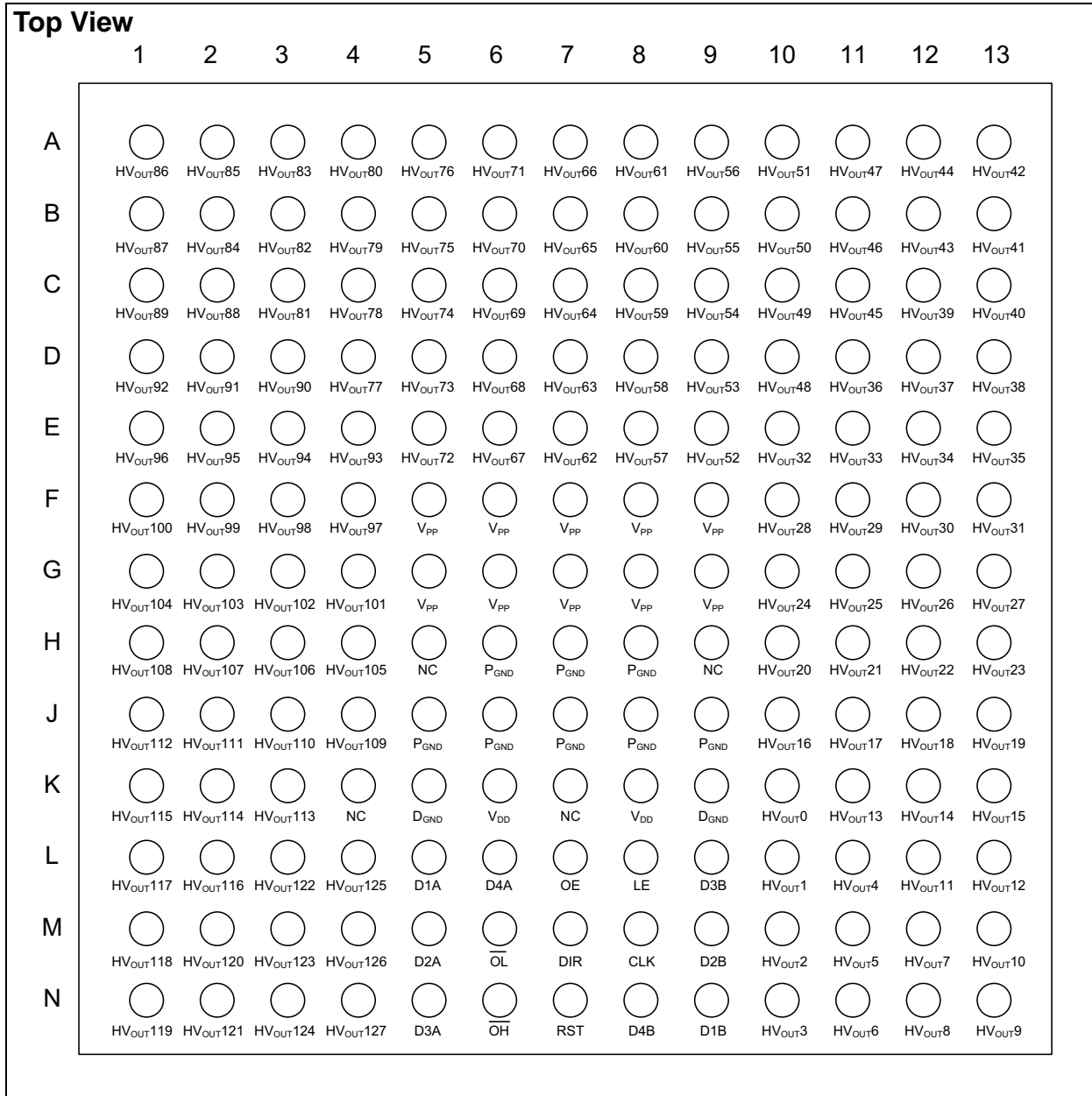
## 1.2 Timing Diagram



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## 2.0 PACKAGE PIN CONFIGURATIONS AND FUNCTION DESCRIPTION

This section details the pin designation for the 169-Ball TFBGA package (Figure 2-1). The descriptions of the pins are listed in Table 2-1.



**FIGURE 2-1:** 169-Ball TFBGA Package.



**TABLE 2-1: PIN ASSIGNMENT**

Pin #	Name	Pin #	Name	Pin #	Name	Pin #	Name
A1	HV <sub>OUT</sub> 86	D5	HV <sub>OUT</sub> 73	H5, H9, K4, K7	NC	M8	CLK
A2	HV <sub>OUT</sub> 85	D6	HV <sub>OUT</sub> 68	H6, H7, H8, J5, J6, J7, J8, J9	P <sub>GND</sub>	M9	D2B
A3	HV <sub>OUT</sub> 83	D7	HV <sub>OUT</sub> 63	H10	HV <sub>OUT</sub> 20	M10	HV <sub>OUT</sub> 2
A4	HV <sub>OUT</sub> 80	D8	HV <sub>OUT</sub> 58	H11	HV <sub>OUT</sub> 21	M11	HV <sub>OUT</sub> 5
A5	HV <sub>OUT</sub> 76	D9	HV <sub>OUT</sub> 53	H12	HV <sub>OUT</sub> 22	M12	HV <sub>OUT</sub> 7
A6	HV <sub>OUT</sub> 71	D10	HV <sub>OUT</sub> 48	H13	HV <sub>OUT</sub> 23	M13	HV <sub>OUT</sub> 10
A7	HV <sub>OUT</sub> 66	D11	HV <sub>OUT</sub> 36	J1	HV <sub>OUT</sub> 112	N1	HV <sub>OUT</sub> 119
A8	HV <sub>OUT</sub> 61	D12	HV <sub>OUT</sub> 37	J2	HV <sub>OUT</sub> 111	N2	HV <sub>OUT</sub> 121
A9	HV <sub>OUT</sub> 56	D13	HV <sub>OUT</sub> 38	J3	HV <sub>OUT</sub> 110	N3	HV <sub>OUT</sub> 124
A10	HV <sub>OUT</sub> 51	E1	HV <sub>OUT</sub> 96	J4	HV <sub>OUT</sub> 109	N4	HV <sub>OUT</sub> 127
A11	HV <sub>OUT</sub> 47	E2	HV <sub>OUT</sub> 95	J10	HV <sub>OUT</sub> 16	N5	D3A
A12	HV <sub>OUT</sub> 44	E3	HV <sub>OUT</sub> 94	J11	HV <sub>OUT</sub> 17	N6	$\overline{\text{OH}}$
A13	HV <sub>OUT</sub> 42	E4	HV <sub>OUT</sub> 93	J12	HV <sub>OUT</sub> 18	N7	RST
B1	HV <sub>OUT</sub> 87	E5	HV <sub>OUT</sub> 72	J13	HV <sub>OUT</sub> 19	N8	D4B
B2	HV <sub>OUT</sub> 84	E6	HV <sub>OUT</sub> 67	K1	HV <sub>OUT</sub> 115	N9	D1B
B3	HV <sub>OUT</sub> 82	E7	HV <sub>OUT</sub> 62	K2	HV <sub>OUT</sub> 114	N10	HV <sub>OUT</sub> 3
B4	HV <sub>OUT</sub> 79	E8	HV <sub>OUT</sub> 57	K3	HV <sub>OUT</sub> 113	N11	HV <sub>OUT</sub> 6
B5	HV <sub>OUT</sub> 75	E9	HV <sub>OUT</sub> 52	K5, K9	D <sub>GND</sub>	N12	HV <sub>OUT</sub> 8
B6	HV <sub>OUT</sub> 70	E10	HV <sub>OUT</sub> 32	K6, K8	V <sub>DD</sub>	N13	HV <sub>OUT</sub> 9
B7	HV <sub>OUT</sub> 65	E11	HV <sub>OUT</sub> 33	K10	HV <sub>OUT</sub> 0		
B8	HV <sub>OUT</sub> 60	E12	HV <sub>OUT</sub> 34	K11	HV <sub>OUT</sub> 13		
B9	HV <sub>OUT</sub> 55	E13	HV <sub>OUT</sub> 35	K12	HV <sub>OUT</sub> 14		
B10	HV <sub>OUT</sub> 50	F1	HV <sub>OUT</sub> 100	K13	HV <sub>OUT</sub> 15		
B11	HV <sub>OUT</sub> 46	F2	HV <sub>OUT</sub> 99	L1	HV <sub>OUT</sub> 117		
B12	HV <sub>OUT</sub> 43	F3	HV <sub>OUT</sub> 98	L2	HV <sub>OUT</sub> 116		
B13	HV <sub>OUT</sub> 41	F4	HV <sub>OUT</sub> 97	L3	HV <sub>OUT</sub> 122		
C1	HV <sub>OUT</sub> 89	F5, F6, F7, F8, F9, G5, G6, G7, G8, G9	V <sub>PP</sub>	L4	HV <sub>OUT</sub> 125		
C2	HV <sub>OUT</sub> 88	F10	HV <sub>OUT</sub> 28	L5	D1A		
C3	HV <sub>OUT</sub> 81	F11	HV <sub>OUT</sub> 29	L6	D4A		
C4	HV <sub>OUT</sub> 78	F12	HV <sub>OUT</sub> 30	L7	OE		
C5	HV <sub>OUT</sub> 74	F13	HV <sub>OUT</sub> 31	L8	LE		
C6	HV <sub>OUT</sub> 69	G1	HV <sub>OUT</sub> 104	L9	D3B		
C7	HV <sub>OUT</sub> 64	G2	HV <sub>OUT</sub> 103	L10	HV <sub>OUTN</sub> 1		
C8	HV <sub>OUT</sub> 59	G3	HV <sub>OUT</sub> 102	L11	HV <sub>OUT</sub> 4		
C9	HV <sub>OUT</sub> 54	G4	HV <sub>OUT</sub> 101	L12	HV <sub>OUT</sub> 11		
C10	HV <sub>OUT</sub> 49	G10	HV <sub>OUT</sub> 24	L13	HV <sub>OUT</sub> 12		
C11	HV <sub>OUT</sub> 45	G11	HV <sub>OUT</sub> 25	M1	HV <sub>OUT</sub> 118		
C12	HV <sub>OUT</sub> 39	G12	HV <sub>OUT</sub> 26	M2	HV <sub>OUT</sub> 120		
C13	HV <sub>OUT</sub> 40	G13	HV <sub>OUT</sub> 27	M3	HV <sub>OUT</sub> 123		
D1	HV <sub>OUT</sub> 92	H1	HV <sub>OUT</sub> 108	M4	HV <sub>OUT</sub> 126		
D2	HV <sub>OUT</sub> 91	H2	HV <sub>OUT</sub> 107	M5	D2A		
D3	HV <sub>OUT</sub> 90	H3	HV <sub>OUT</sub> 106	M6	$\overline{\text{OL}}$		
D4	HV <sub>OUT</sub> 77	H4	HV <sub>OUT</sub> 105	M7	DIR		

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## 2.1 High-Voltage Output Pins (HV<sub>OUT0</sub> to HV<sub>OUT127</sub>)

These are the high-voltage output channels (Push-Pull).

## 2.2 High-Voltage Power Supply Pins (V<sub>PP</sub>)

High-voltage power supply pins for the output channels (HV<sub>OUTn</sub>).

## 2.3 No Connection Pins (NC)

NC pins do not have any functionality on the IC. These pins should not be connected.

## 2.4 High-Voltage Ground Pins (P<sub>GND</sub>)

High-voltage ground pins provide the reference ground level for the high-voltage output channels.

## 2.5 Digital Logic Ground Pins (D<sub>GND</sub>)

Digital Logic Ground pins provide a reference ground level for the low-voltage section of the IC, shift-registers, latches and decoders.

## 2.6 Logic Power Supply Pins (V<sub>DD</sub>)

Logic power supply pins for the 32-bit shift registers, 128-bit latch and decoders.

## 2.7 Data Input/Output Pins (D1A, D2A, D3A, D4A)

Data Input/Output pins are configurable as inputs or outputs for the shift registers depending on the state of the Direction pin (DIR).

When DIR is High, pins D1A to D4A are configured as inputs to the data shift registers. When DIR is Low, these pins are configured as outputs of the data shift registers.

## 2.8 Output Enable Pin (OE)

The Output Enable pin controls the functionality of the high-voltage output channels.

When OE is High, all HV<sub>OUTn</sub> channels are enabled and form a push-pull configuration to operate according to input data,  $\overline{OL}$  or  $\overline{OH}$  configuration states. When OE is Low, all HV<sub>OUTn</sub> channels are forced to a high-impedance state, regardless of the data stored in the 128-bit latch or the state of the  $\overline{OL}$  and  $\overline{OH}$  pins.

## 2.9 Latch Enable Pin (LE)

The Latch Enable pin controls the data transfer from the input shift registers to the 128-bit latch and the HV<sub>OUTn</sub> channels.

When LE transitions from Low to High (rising edge), data is transferred from the 128-bit data latch to the HV<sub>OUTn</sub> output channels. When LE is Low, new data can be clocked into the shift registers.

## 2.10 Data Input/Output Pins (D1B, D2B, D3B, D4B)

Data Input/Output pins are configurable as inputs or outputs for the shift registers, depending on the state of the Direction pin (DIR).

When DIR is Low, pins D1B to D4B are configured as inputs to the data shift registers. When DIR is High, pins are configured as outputs of the data shift registers.

## 2.11 Output Low Pin ( $\overline{OL}$ )

The Output Low pin sets all high-voltage output channels (HV<sub>OUT0</sub> to HV<sub>OUT127</sub>) to a Low-level state (P<sub>GND</sub>).

When  $\overline{OL}$  is set Low and OE is High, all the HV<sub>OUTn</sub> channels are forced to a Low-level state (P<sub>GND</sub>), regardless of the data stored in the 128-bit latch.

## 2.12 Direction Pin (DIR)

The DIR pin controls the direction of the input data flow for the input registers, whether it is clockwise (DnB to DnA) or counter-clockwise (DnA to DnB).

When the DIR pin is set High, data flows from DnA to DnB. When DIR pin is set Low, data flows from DnB to DnA. See [Table 1-6](#) for more information.

## 2.13 Clock Input Pin (CLK)

This is the Clock Input pin for 32-bit input shift registers.

## 2.14 Output High Pin ( $\overline{OH}$ )

The Output High pin sets all high-voltage output channels (HV<sub>OUT0</sub> to HV<sub>OUT127</sub>) to a High-level state (V<sub>PP</sub>).

When  $\overline{OH}$  is Low while OE and  $\overline{OL}$  are High, all the HV<sub>OUTn</sub> channels are forced to a High-level state (V<sub>PP</sub>), regardless of the data stored in the 128-bit latch. See [Table 1-4](#) for more information.

## 2.15 Reset Pin (RST)

The RST pin clears shift registers and the 128-bit latch data content when it is set High during the rising edge of the CLK and LE, respectively. See [Table 1-5](#) for more information.

## 3.0 FUNCTIONAL DESCRIPTION

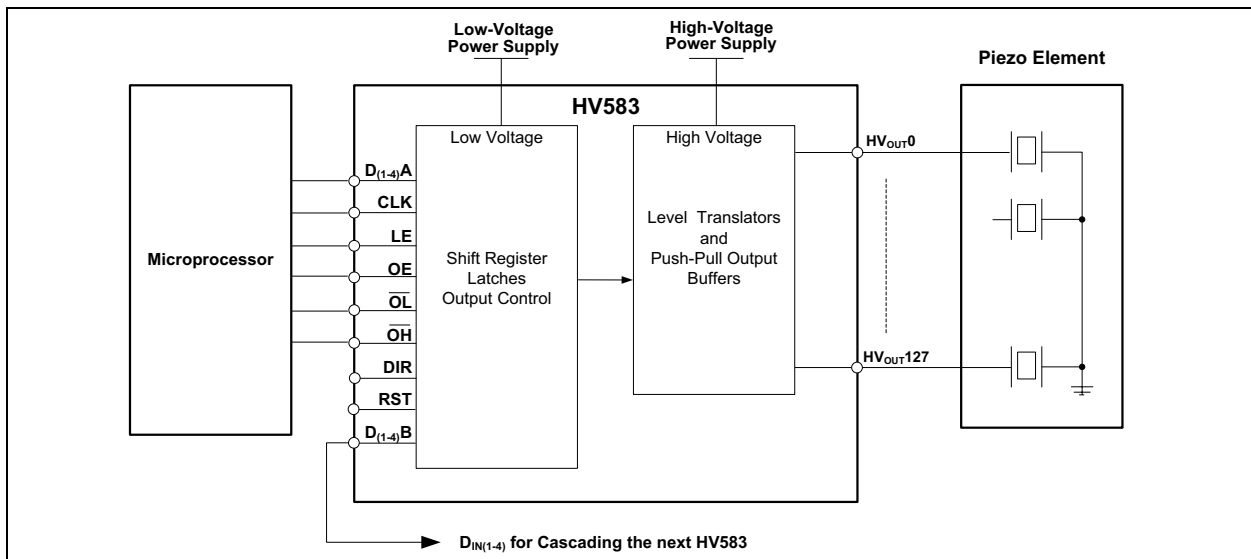
The HV583 is a unipolar, 128-channel low-voltage serial to high-voltage parallel converter. The device consists of four parallel 32-bit shift registers, a 128-bit latch and 128 high-voltage outputs.

The four independent shift registers allow data to be updated into the 128-bit latch at four times the speed of a single register, providing a fast update rate for the 128 output channels. The 128-bit latch holds the data for the high-voltage output channels; whether it is a High-level or Low-level state. The flow of the input data can switch direction from clockwise (DnB to DnA) to counter-clockwise (DnA to DnB) by controlling the DIR pin. A reset pin (RST) is provided to clear the contents of the latches. All channels can be set at the same time to a high-impedance state (High Z), Low-level state, or High-level state through the OE,  $\overline{OL}$  and  $\overline{OH}$  pins, respectively.

The high-output voltages ( $HV_{OUTn}$ ) can operate from 15V to 80V with a maximum current source and sink capability of 30 mA.

## 3.1 Application Information

HV583 is designed for applications requiring multiple high-voltage outputs with current sinking and sourcing capabilities in the range of  $\pm 30$  mA. Typical applications where the HV583 is utilized are in plasma displays, Inkjet printer drivers and 3D printer drivers.



**FIGURE 3-1:** Typical Application Block Diagram.

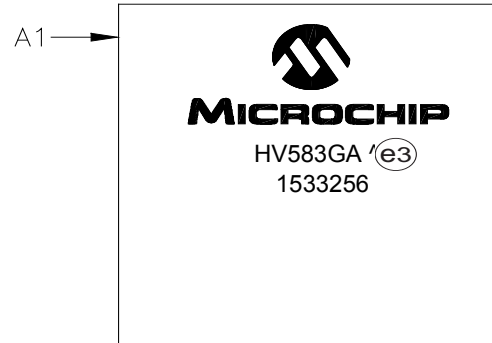
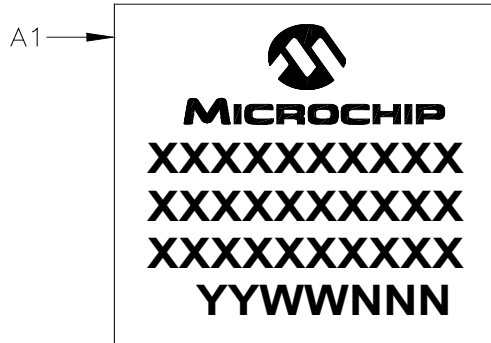
# HV583

## 4.0 PACKAGING INFORMATION

### 4.1 Package Marking Information

169-Ball TFBGA (10 x10 x1.1 mm)

Example

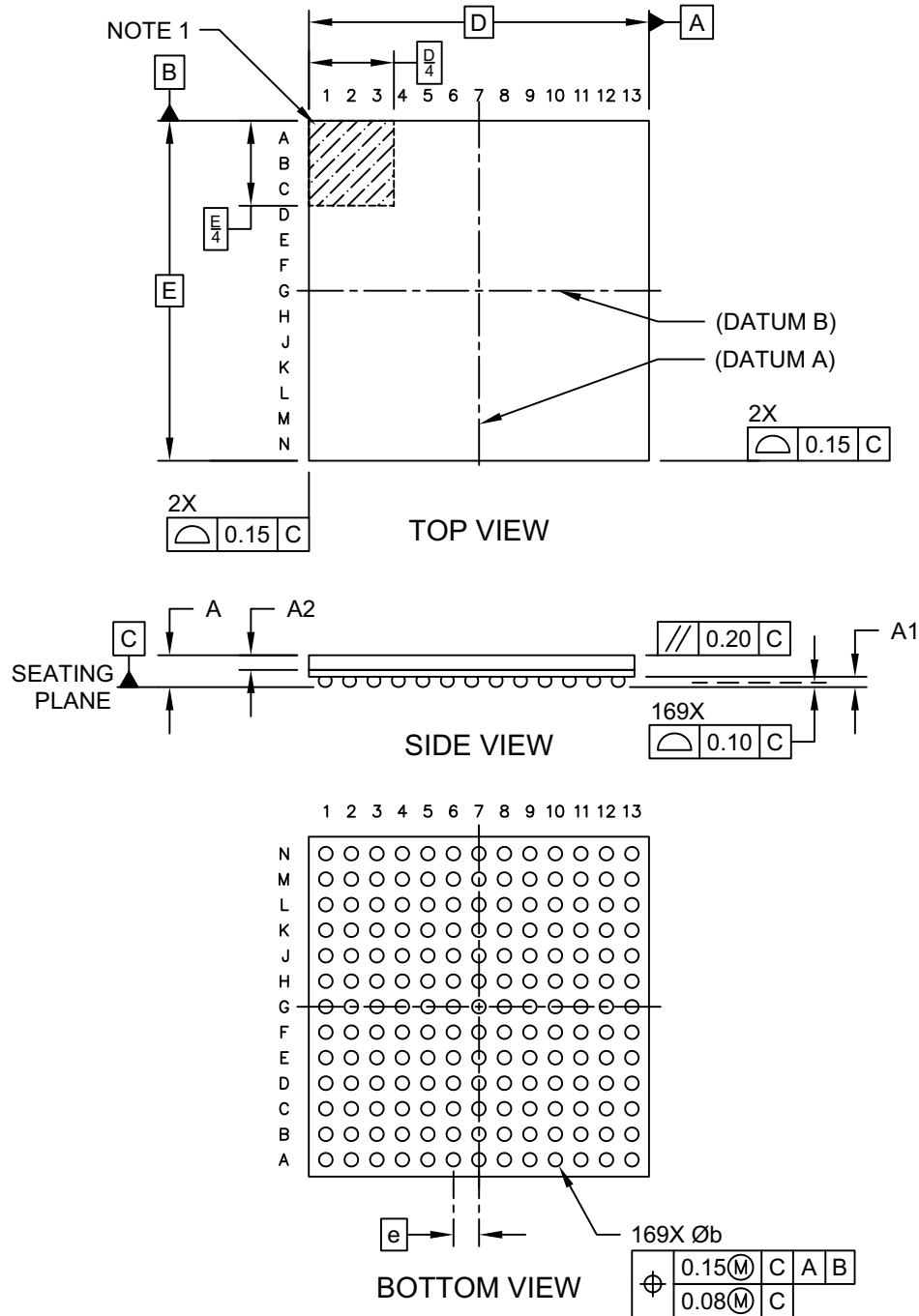


<b>Legend:</b>	XX...X	Product Code or Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

**Note:** In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.

## 169-Ball Thin Fine Pitch Ball Grid Array (7G) - 10x10x1.10 mm Body [TFBGA] (Complies with JEDEC Terminal Assignment recommendations)

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

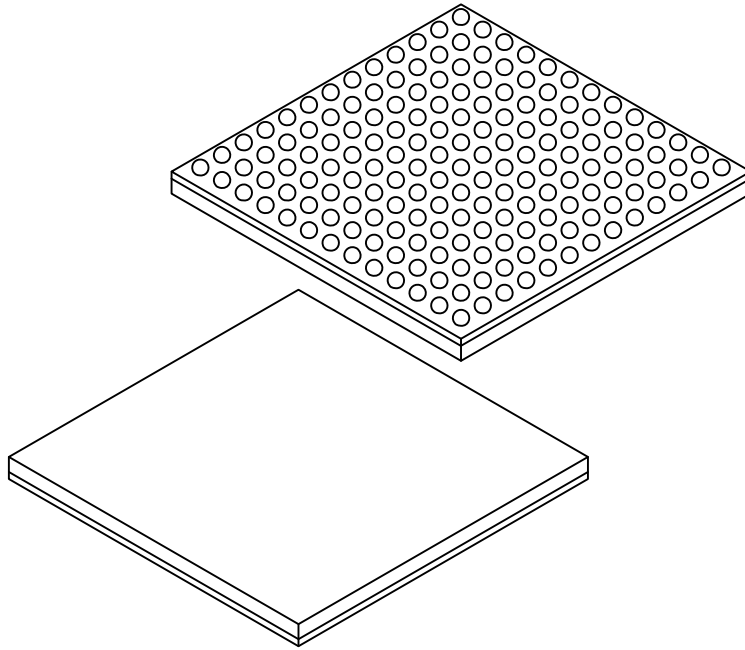


Microchip Technology Drawing C04-377-J Rev C Sheet 1 of 2

# HV583

## 169-Ball Thin Fine Pitch Ball Grid Array (7G) - 10x10x1.10 mm Body [TFBGA] (Complies with JEDEC Terminal Assignment recommendations)

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		169		
Pitch	e		0.75 BSC		
Overall Height	A		-	-	1.10
Standoff	A1		0.21	0.32	-
Mold Cap Thickness	A2		0.50	0.45	0.50
Overall Length	D		10.00		
Overall Width	E		10.00		
Ball Diameter	b		0.35	0.40	0.45

Notes:

1. Terminal A1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

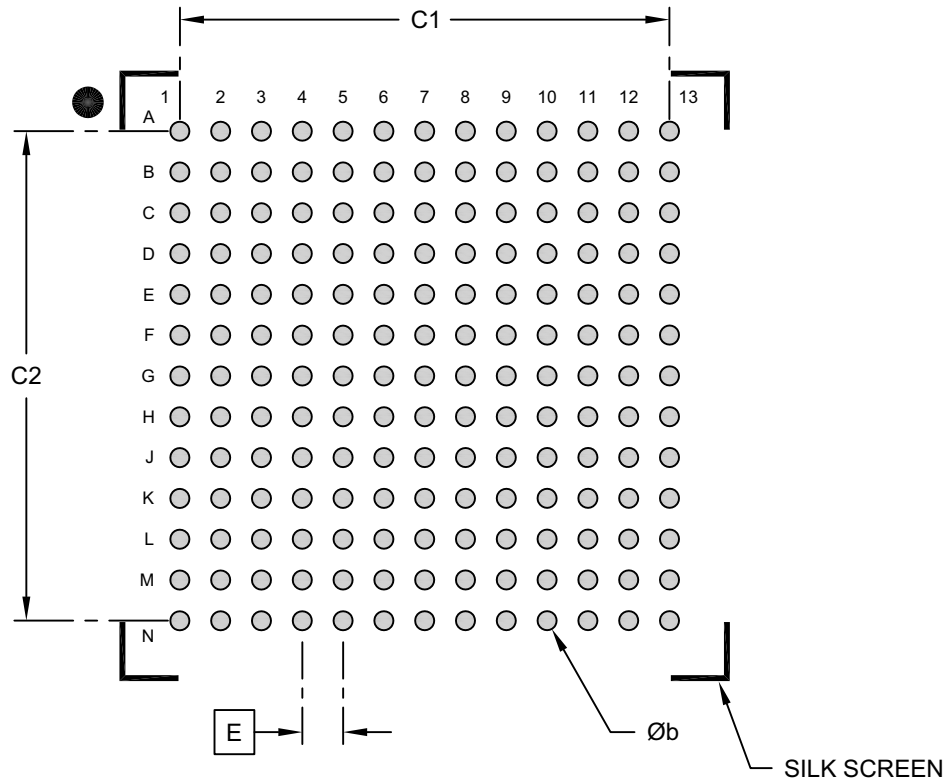
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-377-J Rev C Sheet 2 of 2

## 169-Ball Thin Fine Pitch Ball Grid Array (7G) - 10x10x1.10 mm Body [TFBGA] (Complies with JEDEC Terminal Assignment recommendations)

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



### RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.75 BSC		
Contact Pad Spacing	C1		9.00	
Contact Pad Spacing	C2		9.00	
Contact Pad Diameter (X169)	b		0.35	

**Notes:**

1. Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2377-J Rev C

# HV583

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NOTES:



## APPENDIX A: REVISION HISTORY

### Revision A (December 2015)

- Original release of this document.

# HV583

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NOTES:

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>XX-X</u>
Device	Package
<b>Device:</b>	HV583: Low-Voltage Serial to High-Voltage Parallel Converter with HV Outputs
<b>Package:</b>	GA-G = Thin Fine Pitch Ball Grid Array - 10 x 10 x 1.1 mm Body, 169-lead (TFBGA)

**Examples:**  
a) HV583GA-G: 169-Ball 10x10 TFBGA Package

# HV583

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NOTES:

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**Note the following details of the code protection feature on Microchip devices:**

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable.”

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ISBN: 978-1-5224-0106-3

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